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## **Body Style:** Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.010 **Terminal Length:** 0.5 millimeters **Body Length:** 3.2 millimeters **Body Width:** 1.6 millimeters **Body Height:** 1.3 millimeters Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 10000.0 megohms **Capacitance Value Per Section:** 20.000 picofarads single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: 0.0 single section Nonderated Continuous Voltage Rating And Type Per Section: 100.0 dc single section **Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:** -30.0/+30.0 single section **Tolerance Range Per Section:** -10.00/+10.00 percent single section **Case Material:** Ceramic Insulation Resistance At Reference Temp: 100000.0 megohms **Dissipation Factor At Reference Tempurature In Percent:** 0.150 **Terminal Surface Treatment:** Solder **Test Data Document:** 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain

environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

## Terminal Type And Quantity:

2 bonding pad



**Specification Data:** 

81349-mil-c-55681/8 government specification

Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

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